Final Product/Process Change Notification

Document #:FPCN25188Z3
Issue Date:09 May 2025

Title of Change:	Update to **FPCN25188Z1** - Remove 3 parts from the affected OPNs and will no longer undergo the change described in previous FPCN.
Proposed Changed Material First Ship Date:	N/A
Current Material Last Order Date:	N/A *Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability*.
Current Material Last Delivery Date:	N/A *The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory*
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	N/A
PPAP Availability Date:	N/A
Additional Reliability Data:	Contact your local onsemi Sales Office
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and its conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.

Change Category

Category	**Type of Change**
Test Flow	SEM-TF-01: Move of all or part of electrical wafer test and/or final test to a different test site.
Equipment	SEM-EQ-02: Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process., SEM-EQ-03: Change in final test equipment type leading to a different test concept.
Process - Assembly	SEM-PA-18: Move all or parts of production to a different assembly site., SEM-PA-11: Change of mold compound / encapsulation material, SEM-PA-07: Die attach material

Description and Purpose:

This Update Notification informs customers that the three parts listed in this PCN document will no longer undergo the change described in **FPCN25188Z1**. These parts will not be assembled and tested at JCET, China. Instead, they will remain in assembly and testing at onsemi Vietnam.

All parts not specifically listed in this update notice will be changed according to the original notification in **FPCN25188Z1**.

Reason / Motivation for Change:	Capacity improvement
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
None	JCET, China

Marking of Parts/ Traceability of Change:	Traceable by Date Code and Assembly marking

Reliability Data Summary: N/A

Electrical Characteristics Summary: N/A

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal*****.**

Current Part Number	New Part Number	Qualification Vehicle
NCV8406BDTRKG	#NONE	NCV8406ADTRKG
NCV8403BDTRKG	#NONE	NCV8401ADTRKG
NCV8401BDTRKG	#NONE	NCV8401ADTRKG